Ankit More

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RESEARCH

Digital, Analog and Mixed Signal Integrated Circuits, Radio Frequency Integrated Circuits (RFIC),

INTERESTS Low Power VLSI Circuits, 3-D ICs and Post-CMOS Interconnects.

EDUCATION \diamond **Ph.D.**, **Electrical Engineering**, (September 2009 – current).

Drexel University, Philadelphia, PA.

Topic: Wireless interconnects for inter and intra-chip communication

♦ M.S., Electrical Engineering, GPA: 3.95 (Summa-cum-laude), (June 2009).

Drexel University, Philadelphia, PA. Concentration: Systems and Control

♦ **B.S., Electrical Engineering**, GPA: 3.95 (Summa-cum-laude), (June 2009).

Drexel University, Philadelphia, PA. Concentration: Advanced Electronics

PROFESSIONAL & Research Assistant and Teaching Assistant, (September 2009 – current)

EXPERIENCE

Department of Electrical and Computer Engineering

Drexel University, Philadelphia, PA

- Research Assistant in the VLSI Lab working on
 - VLSI design and
 - -3D electro-magnetic modeling.
- Teaching Assistant in the ECE Department for
- Electrical Engineering Laboratory 3 (ECE-L 303) (Fall, AY 2009 2010).
- Electrical Engineering Laboratory 4 (ECE-L 304) (Winter, Summer, AY 2009 2010).
- Introduction to Nuclear Reactor Theory (Spring, AY 2009 2010).

♦ Internship - Research and Development Engineering , (April 2008 – September 2008)

Siemens Energy and Automation, Spring House, PA, USA

- Developed automated software testing tools for distributed control systems software.
- Co-authored patent application for an expandable automated testing concept, awaiting filing of application.
- Assisted in Virtual Machine management using VMWare.

♦ Internship - Assistant Project Manager, (September 2006 – March 2007)

Maida Engineering Inc, Fort Washington, PA, USA

- Assisted in design of power distribution systems to manufacturing plants.
- Created two dimensional CAD layouts using AutoCAD for electrical systems according to the NEC.

SELECTED \diamond Wireless Interconnect Design, Drexel University

PROJECTS

- Design of on-chip antennas for inter and intra-chip communication for planar and 3D ICs.
- IC design in IBM 90 nm technology.
- Full-wave 3D Finite Element Method (FEM) electro-magnetic simulations.
- Simulation of leakage current, electro-magnetic compatibility and interference.

♦ Rotary Clock Custom Integrated Circuit, Drexel University

- Design of custom and regular rotary rings.
- IC design in AMI C5N 0.5 μm process using MOSIS fabrication process.

♦ Senior Design, Unmanned Aerial Vehicle (UAV), Drexel University

- Autonomous control for stable hover of miniature unmanned aerial vehicles.
- Designed a control system using embedded C code on Texas Instruments TMS320 DSP.
- Designed custom peripheral circuits for DSP isolation and sensor connection.
- Co-sponsored by the U.S. Army Research Lab and the MEM Department, Drexel University.

- PUBLICATIONS ♦ Ankit More and Baris Taskin, Wireless Interconnects for Inter-tier Communication on 3-D ICs, to appear in the Proceedings of the European Microwave Integrated Circuits Conference (EuMIC), September 2010.
 - Ankit More and Baris Taskin, Simulation Based Study of On-chip Antennas for a Reconfigurable Hybrid 3D Wireless NoC, to appear in the Proceedings of the IEEE International SoC Conference (SOCC), September 2010.
 - ♦ Ankit More and Baris Taskin, Effect of EMI between Wireless Interconnects and Metal Interconnects on CMOS Digital Circuits, to appear in the Proceedings of the Mediterranean Microwave Symposium (MMS), August 2010.
 - Ankit More and Baris Taskin, Simulation Based Feasibility Study of Wireless RF Interconnects for 3D ICs, Proceedings of the IEEE Computer Society Annual Symposium on VLSI (ISVLSI), July 2010.
 - ♦ Ankit More and Baris Taskin, Electromagnetic Compatibility of CMOS On-chip Antennas, Proceedings of the IEEE International Symposium on Antennas and Propagation (APS), July 2010.
 - Ankit More and Baris Taskin, Simulation Based Study of Wireless RF Interconnects for Practical CMOS Implementation, Proceedings of the System Level Interconnect Prediction (SLIP), June 2010.
 - Ankit More and Baris Taskin, Electromagnetic Interaction of On-Chip Antennas and CMOS Metal Layers for Wireless IC Interconnects, Proceedings of the IEEE/ACM Great Lakes Symposium on VLSI (GLSVLSI), May 2010.
 - Ankit More and Baris Taskin, Leakage Current Analysis for Intra-Chip Wireless Interconnects, Proceedings of the IEEE International Symposium on Quality Electronic Design (ISQED), pp. 49– 53, March 2010.
 - SKILLS & C, C++, Basic Java, CLisp, XML, XSLT, JScript, VBScript
 - ♦ Cadence Virtuoso Suite, Spectre, PSpice Synopsys - Design Compiler, ICC Complier, HSpice
 - ♦ Ansoft High Frequency Structure Simulator (HFSS), Q3D extractor Agilent – Advanced Design Systems (ADS)
 - Matlab, Maple, Labview, AutoCAD, Quick Test Professional
 - ♦ LATEX, Office Suites
 - ♦ Unix, Linux, MS Windows

ACADEMIC ♦ George Hill, Jr. Fellow, Derexel University, 2010 – 2011.

AWARDS

- $HONORS\ AND\ \ \, \diamond\ \, Freshman\ Design\ Fellow\ for\ the\ College\ of\ Engineering,\ Drexel\ University,\ 2010-2011.$
 - ♦ President, Drexel IEEE Graduate Forum, 2010 2011.
 - ♦ Graduated with 1st Honors (highest GPA among the graduating class) from the Department of Electrical and Computer Engineering, Drexel University, 2009.
 - ♦ Dean's List, College of Engineering, Drexel University, 2005 2009.
 - ♦ A.J. Drexel Academic Scholarship, Drexel University, 2005 2009.
 - ♦ John Raymond Vollmar Endowed Scholarship, Drexel University, 2007 2008.
 - ♦ Harry E. Muchnic Scholarship, Drexel University, 2008 2009.
 - ♦ Tau Beta Pi National Scholarship, 2008 2009.
 - Member, Tau Beta Pi, Engineering Honor Society.
 - ♦ Member, Eta Kappa Nu, Electrical Engineering Honor Society.

COURSEWORK

RELEVANT ♦ CMOS VLSI Design, Computer Architecture, CAD for VLSI Design, Digital IC Design, Stochastic Systems, Microwave Passive Systems, Microwave Active Systems, RF Electronics, Numerical Analysis Methods.

References \diamond **Dr. Moshe Kam**

Department Head and Robert Quinn Professor Department of Electrical and Computer Engineering Drexel University, Philadelphia, PA

E-mail: kam@minerva.ece.drexel.edu

♦ Dr. B.C. Chang

Professor, Department of Mechanical Engineering and Mechanics Drexel University, Philadelphia, PA E-mail: bchang@coe.drexel.edu

♦ Dr. Baris Taskin

Assistant Professor, Department of Electrical and Computer Engineering Drexel University, Philadelphia, PA

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